

Features

- N+P Channel
- Enhancement mode
- Very low on-resistance
- Fast Switching and High efficiency
- 100% Avalanche Tested
- Pb-free lead plating; RoHS compliant

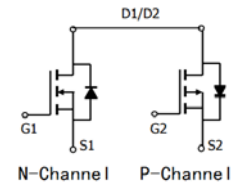


V_{DS}	40	-40	V
$R_{DS(on),TYP}@ V_{GS}=\pm 10V$	12	30	mΩ
$R_{DS(on),TYP}@ V_{GS}=\pm 4.5V$	18	50	mΩ
I_D	40	-25	A

TO-252-4L



Part ID	Package Type	Marking	Tape and reel information
VSD020C04MC	TO-252-4L	020C04MC	2500pcs/Reel



Symbol	Parameter	Rating		Unit	
		NMOS	PMOS		
$V_{(BR)DSS}$	Drain-Source breakdown voltage	40	-40	V	
V_{GS}	Gate-Source voltage	±20	±20	V	
I_S	Diode continuous forward current	$T_C=25^\circ C$	40	-25	A
I_D	Continuous drain current @ $V_{GS}=\pm 10V$	$T_C=25^\circ C$	40	-25	A
		$T_C=100^\circ C$	28	-18	A
I_{DM}	Pulse drain current tested ①	$T_C=25^\circ C$	160	-100	A
I_{DSM}	Continuous drain current @ $V_{GS}=\pm 10V$	$T_A=25^\circ C$	7	-5	A
		$T_A=70^\circ C$	6	-4	A
EAS	Avalanche energy, single pulsed ②		16	20	mJ
P_D	Maximum power dissipation	$T_C=25^\circ C$	38	38	W
P_{DSM}	Maximum power dissipation ③	$T_A=25^\circ C$	1.3	1.3	W
T_{STG}, T_J	Storage and junction temperature range		-55 to 175	-55 to 175	°C

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	3.9	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	100	°C/W

N-Channel Electrical Characteristics

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	40	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current(T _C =25°C)	V _{DS} =40V, V _{GS} =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(T _C =125°C)	V _{DS} =40V, V _{GS} =0V	--	--	100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.3	1.8	2.5	V
R _{DS(ON)}	Drain-Source On-State Resistance ④	V _{GS} =10V, I _D =20A	--	12	17	mΩ
		T _C =100°C	--	15	--	mΩ
		V _{GS} =4.5V, I _D =10A	--	18	25	mΩ
Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
C _{iss}	Input Capacitance	V _{DS} =20V, V _{GS} =0V, f=1MHz	1120	1320	1520	pF
C _{oss}	Output Capacitance		85	100	115	pF
C _{rss}	Reverse Transfer Capacitance		70	80	90	pF
R _g	Gate Resistance	f=1MHz	--	1.9	--	Ω
Q _g (10V)	Total Gate Charge	V _{DS} =20V, I _D =20A, V _{GS} =10V	--	22	--	nC
Q _g (4.5V)	Total Gate Charge		--	10	--	nC
Q _{gs}	Gate Source Charge		--	5.3	--	nC
Q _{gd}	Gate Drain Charge		--	3.7	--	nC
Switching Characteristics						
t _{d(on)}	Turn on Delay Time	V _{DD} =20V, I _D =20A, R _G =3Ω, V _{GS} =10V	--	8.2	--	ns
t _r	Turn on Rise Time		--	56	--	ns
t _{d(off)}	Turn Off Delay Time		-	19	--	ns
t _f	Turn Off Fall Time		--	40	--	ns
Source Drain Diode Characteristics						
V _{SD}	Forward on voltage	I _{SD} =20A, V _{GS} =0V	--	0.9	1.2	V
t _{rr}	Reverse Recovery Time	T _J =25°C, I _{sd} =20A, V _{GS} =0V	--	12	--	ns
Q _{rr}	Reverse Recovery Charge	di/dt=-100A/μs	--	5.3	--	nC

NOTE: ① Repetitive rating; pulse width limited by max junction temperature.

② Limited by T_{Jmax}, starting T_J = 25°C, L = 0.5mH, R_G = 25Ω, I_{AS} = 8A, V_{GS} = 10V. Part not recommended for use above this value

③ The power dissipation P_{DSM} is based on R_{θJA} and the maximum allowed junction temperature of 150°C.

④ Pulse width ≤ 380μs; duty cycle ≤ 2%.

P-Channel Electrical Characteristics

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-40	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current(T _C =25°C)	V _{DS} =-40V, V _{GS} =0V	--	--	-1	μA
	Zero Gate Voltage Drain Current(T _C =125°C)	V _{DS} =-40V, V _{GS} =0V	--	--	-100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1.3	-1.8	-2.5	V
R _{DS(ON)}	Drain-Source On-State Resistance ④	V _{GS} =-10V, I _D =-20A	--	30	40	mΩ
		T _C =100°C	--	35	--	mΩ
		V _{GS} =-4.5V, I _D =-15A	--	50	65	mΩ
Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
C _{iss}	Input Capacitance	V _{DS} =-20V, V _{GS} =0V, f=1MHz	1100	1300	1500	pF
C _{oss}	Output Capacitance		90	110	130	pF
C _{rss}	Reverse Transfer Capacitance		70	85	100	pF
R _g	Gate Resistance	f=1MHz	--	7.1	--	Ω
Q _g (-10V)	Total Gate Charge	V _{DS} =-20V, I _D =-20A, V _{GS} =-10V	--	21	--	nC
Q _g (-4.5V)	Total Gate Charge		--	9.3	--	nC
Q _{gs}	Gate Source Charge		--	5.6	--	nC
Q _{gd}	Gate Drain Charge		--	3.5	--	nC
Switching Characteristics						
t _{d(on)}	Turn on Delay Time	V _{DD} =-20V, I _D =-20A, R _G =2.7Ω, V _{GS} =-10V	--	7.2	--	ns
t _r	Turn on Rise Time		--	44	--	ns
t _{d(off)}	Turn Off Delay Time		-	24	--	ns
t _f	Turn Off Fall Time		--	26	--	ns
Source Drain Diode Characteristics						
V _{SD}	Forward on voltage	I _{SD} =-20A, V _{GS} =0V	--	-1	-1.2	V
t _{rr}	Reverse Recovery Time	T _J =25°C, I _{SD} =-20A, V _{GS} =0V	--	13	--	ns
Q _{rr}	Reverse Recovery Charge	di/dt=-100A/μs	--	6.3	--	nC

NOTE: ① Repetitive rating; pulse width limited by max junction temperature.

② Limited by T_{Jmax}, starting T_J = 25°C, L = 0.5mH, R_G = 25Ω, I_{AS} = -9A, V_{GS} = -10V. Part not recommended for use above this value

③ The power dissipation P_{DSM} is based on R_{θJA} and the maximum allowed junction temperature of 150°C.

④ Pulse width ≤ 380μs; duty cycles ≤ 2%.

N-Channel Typical Characteristics

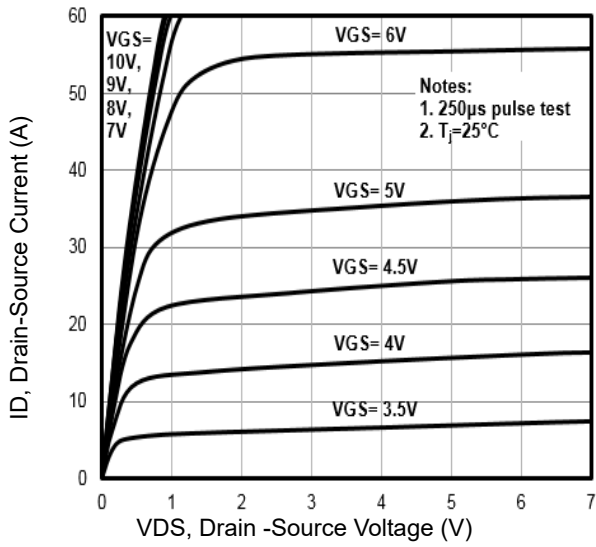


Fig1. Typical Output Characteristics

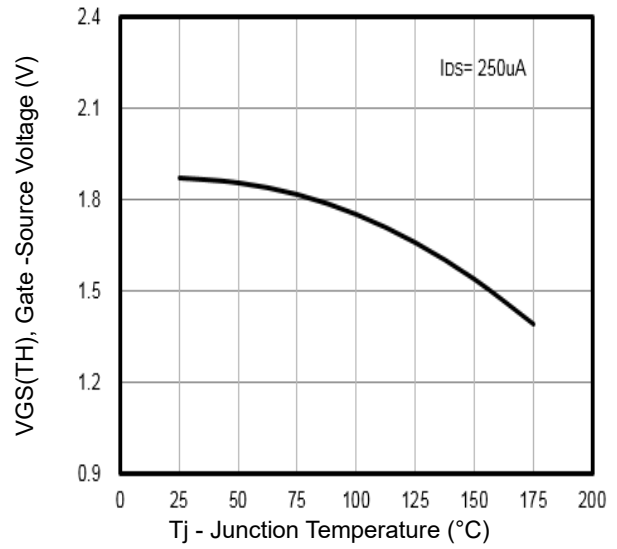


Fig2. $V_{GS(TH)}$ Gate-Source Voltage Vs. T_j

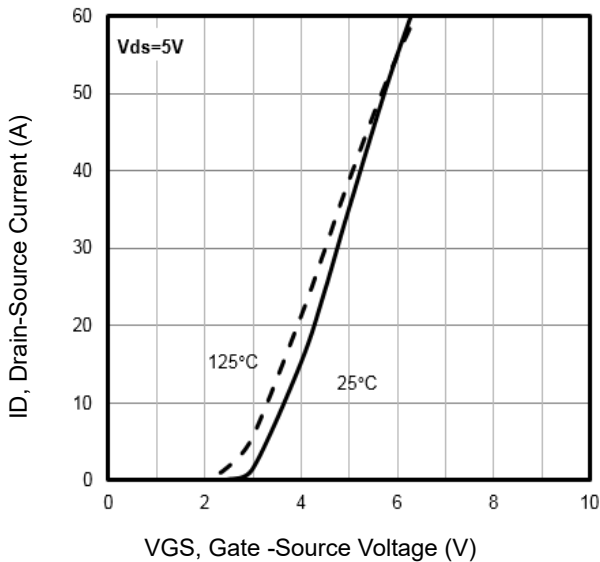


Fig3. Typical Transfer Characteristics

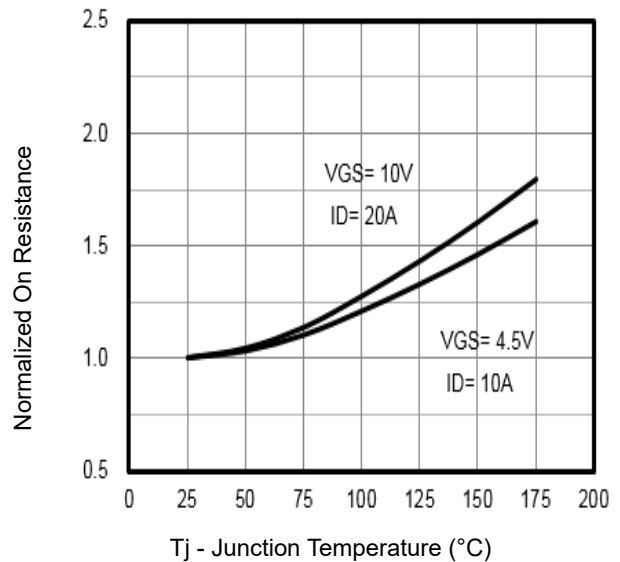


Fig4. Normalized On-Resistance Vs. T_j

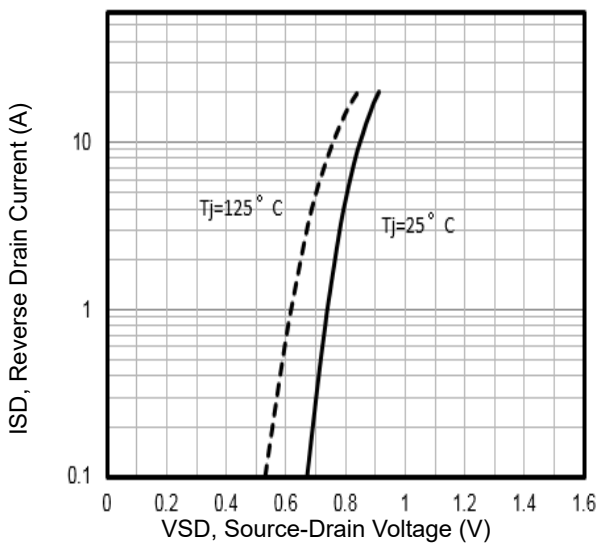


Fig5. Typical Source-Drain Diode Forward Voltage

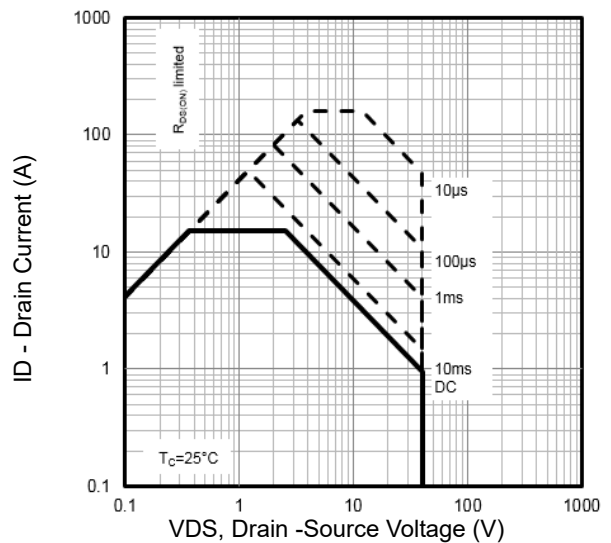


Fig6. Maximum Safe Operating Area

N-Channel Typical Characteristics

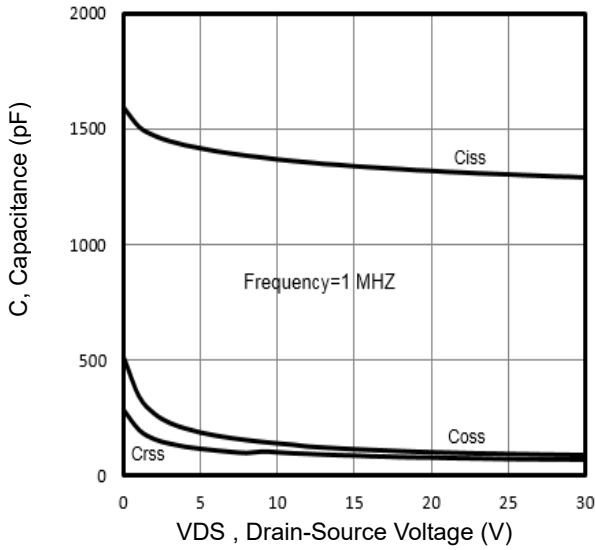


Fig7. Typical Capacitance Vs.Drain-Source Voltage

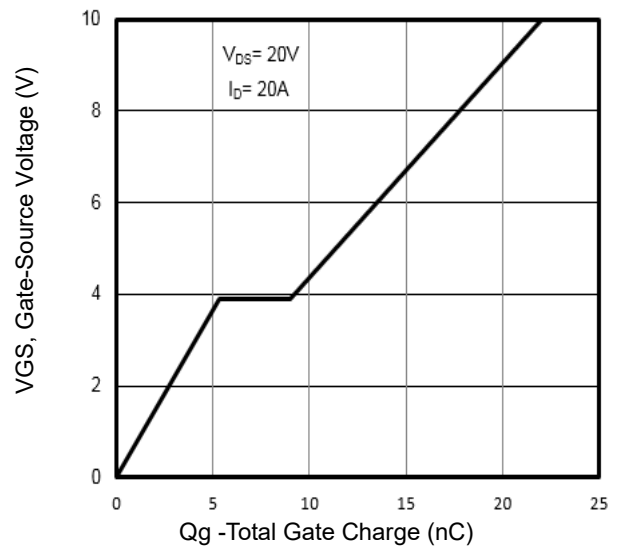


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

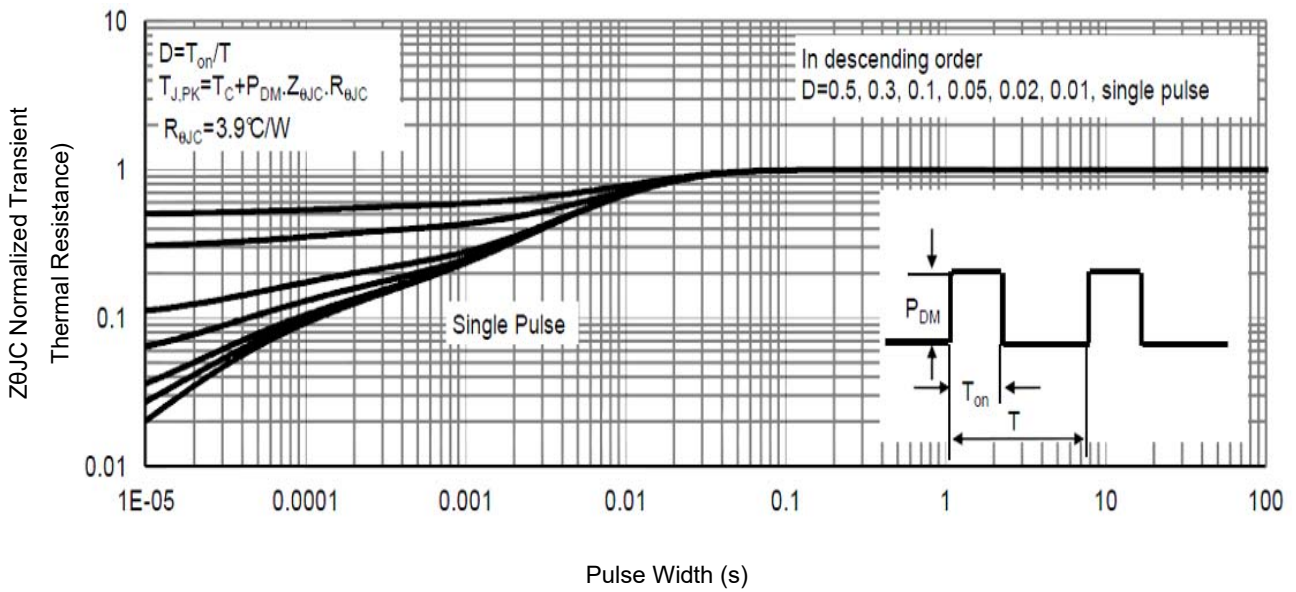


Fig 9 .Normalized Maximum Transient Thermal Impedance

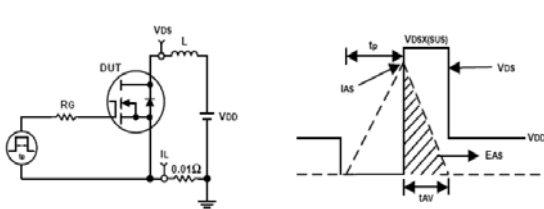


Fig10. Unclamped Inductive Test Circuit and waveforms

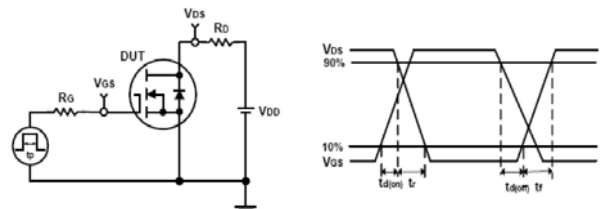


Fig11. Switching Time Test Circuit and waveforms



P-Channel Typical Characteristics

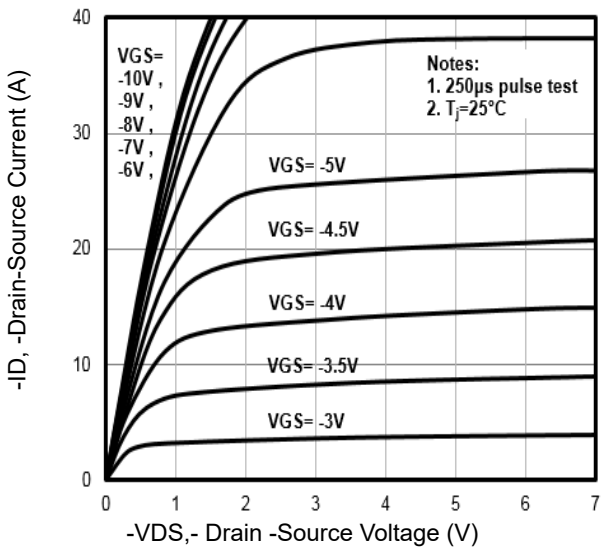


Fig1. Typical Output Characteristics

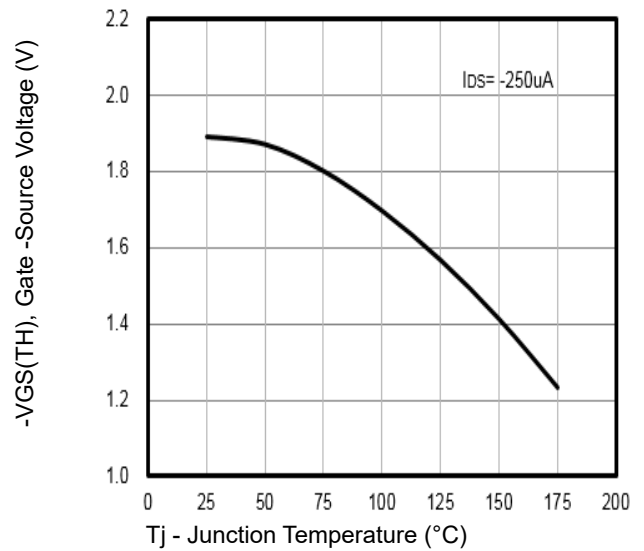


Fig2. V_{GS(TH)} Gate -Source Voltage Vs. T_j

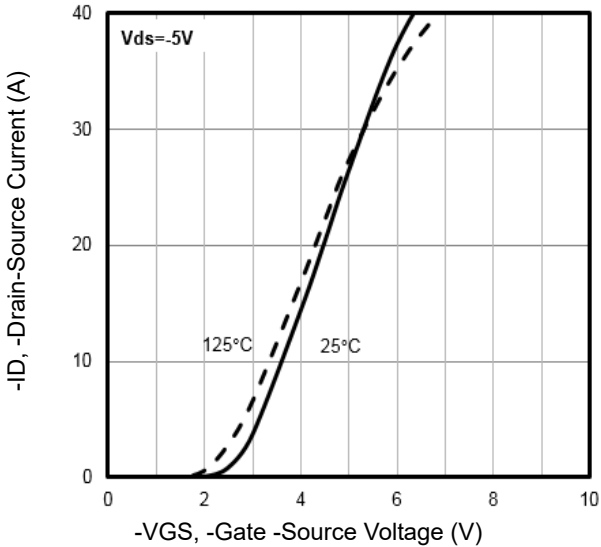


Fig3. Typical Transfer Characteristics

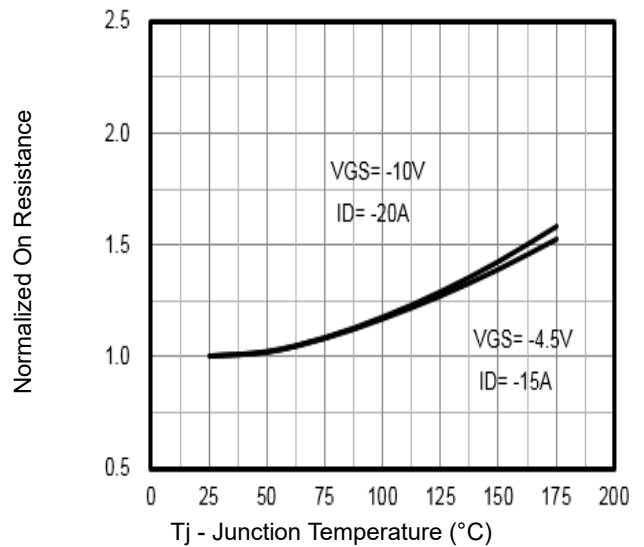


Fig4. Normalized On-Resistance Vs. T_j

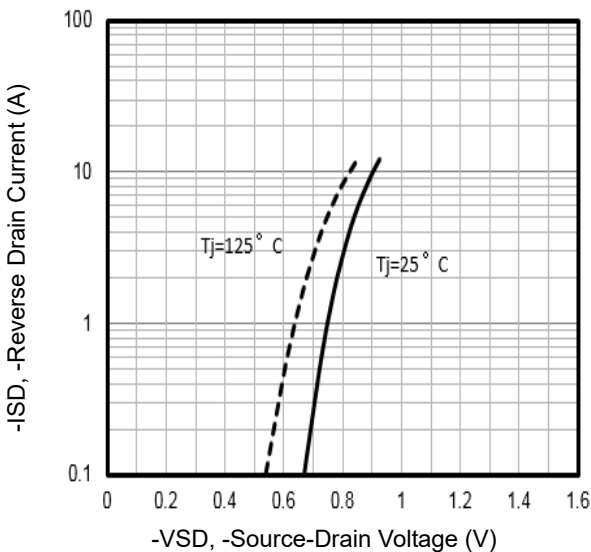


Fig5. Typical Source-Drain Diode Forward Voltage

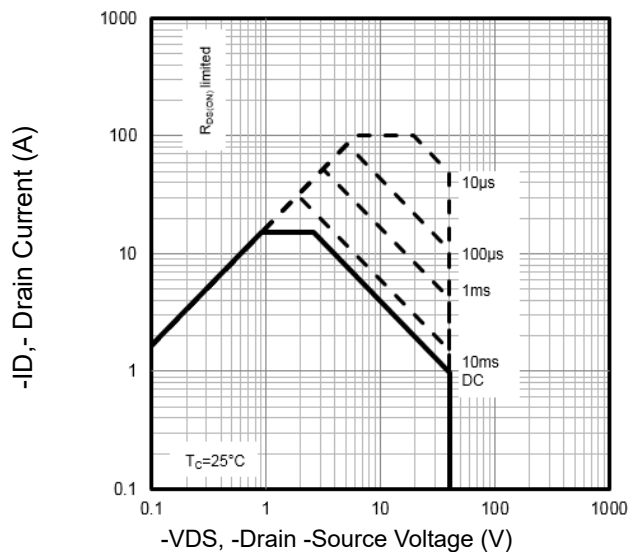


Fig6. Maximum Safe Operating Area

P-Channel Typical Characteristics

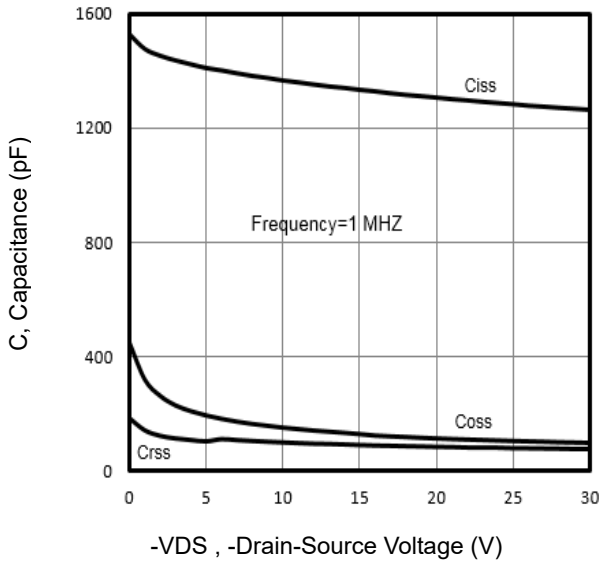


Fig7. Typical Capacitance Vs.Drain-Source Voltage

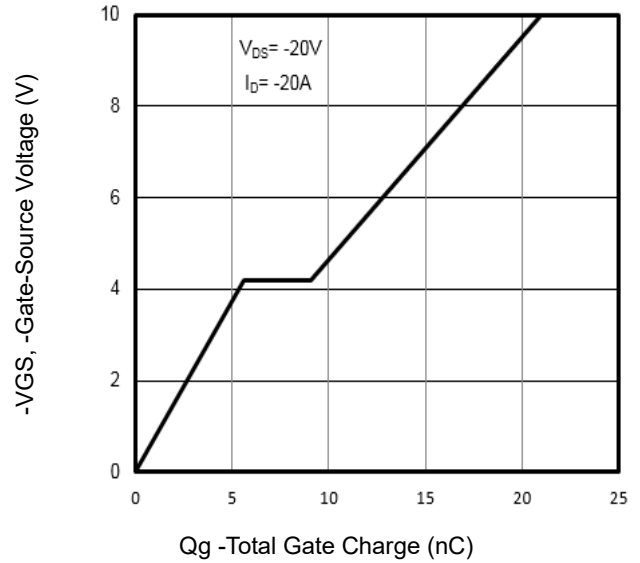


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

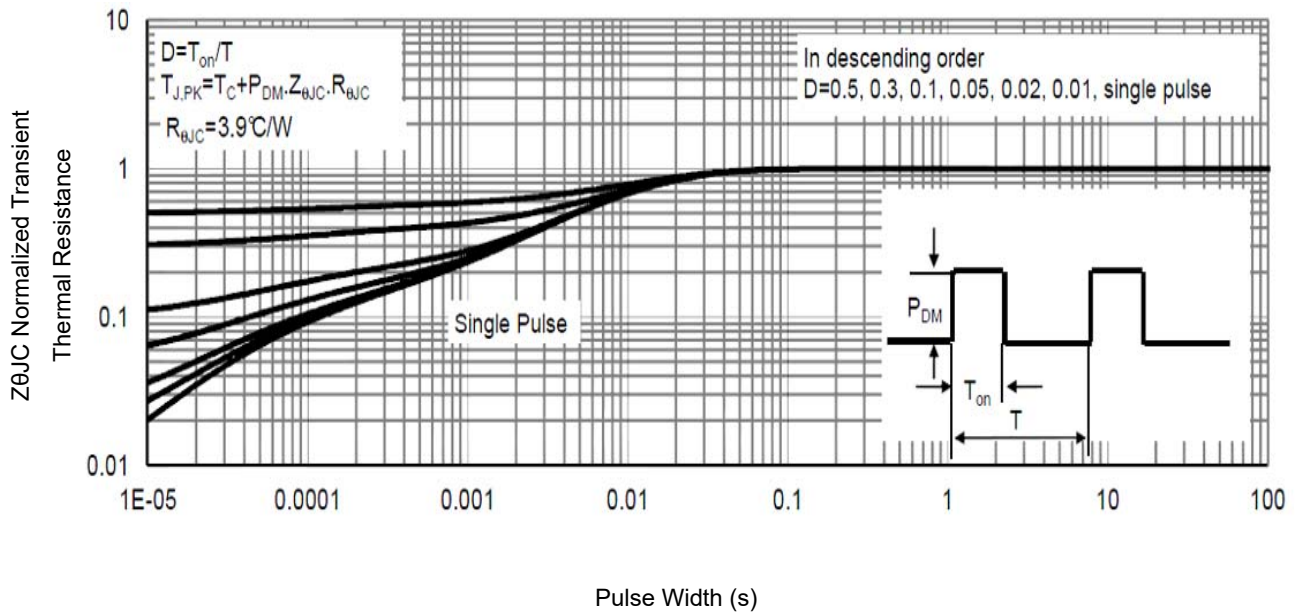


Fig9. Normalized Maximum Transient Thermal Impedance

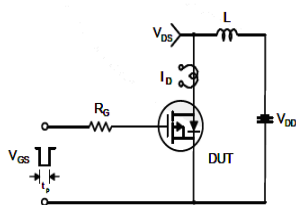


Fig10. Unclamped Inductive Test Circuit and Waveforms

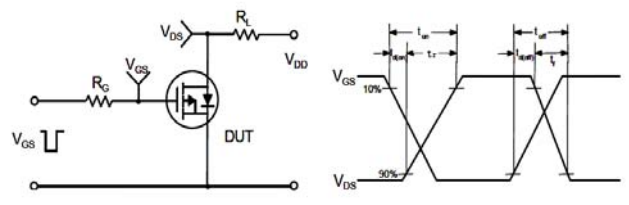
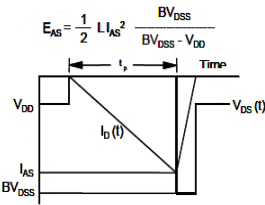
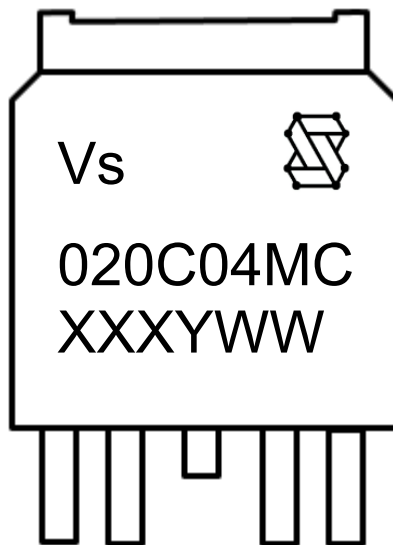


Fig11. Switching Time Test Circuit and waveforms

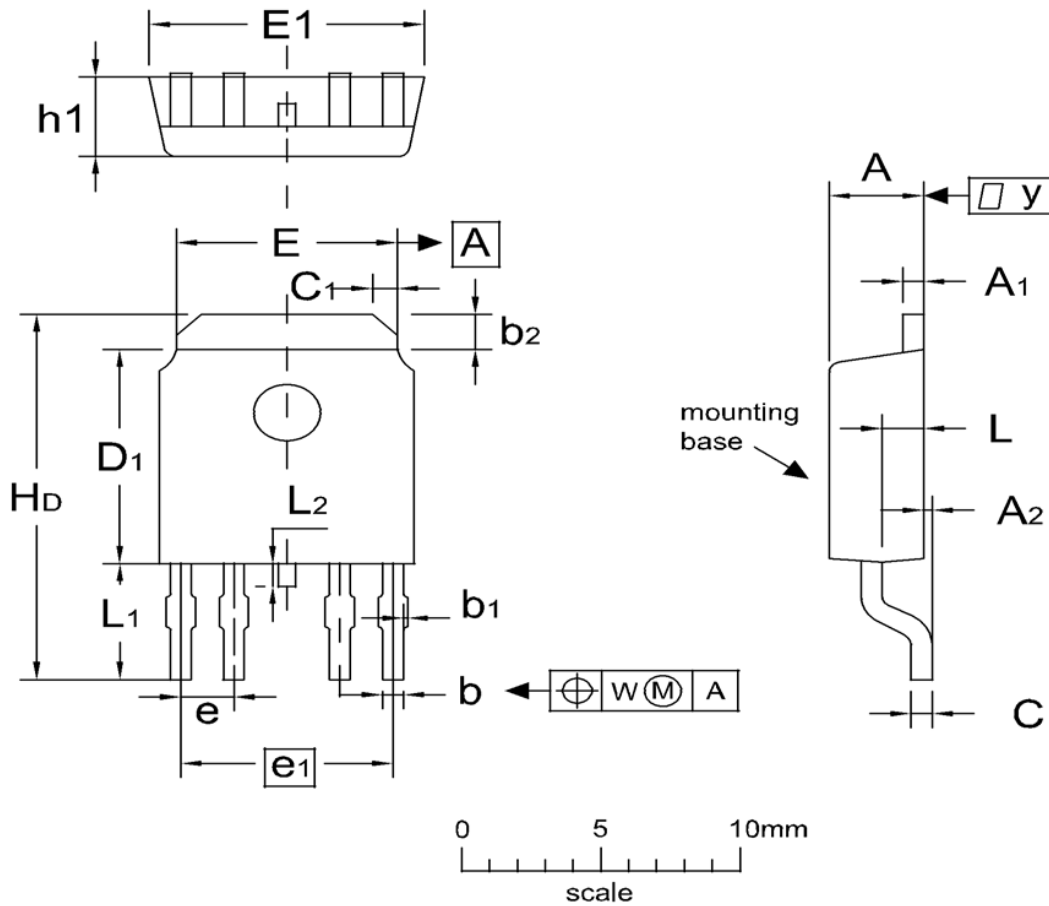
Marking Information



- 1st line: Vanguard Code (Vs), Vanguard Logo
2nd line: Part Number (020C04MC)
3rd line: Date code (XXXYWW)
XXX: Wafer Lot Number Code , code changed with Lot Number
Y: Year Code, (e.g. E=2017, F=2018, G=2019, H=2020, etc)
WW: Week Code (01 to 53)



TO-252-4L Package Outline Data



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	2.1	2.3	2.5	A ₁	0.4	0.5	0.6
A ₂	--	--	0.3	b	0.4	0.5	0.6
b ₁	--	--	0.1	b ₂	0.8	1.0	1.2
C	0.4	0.5	0.6	C ₁	0.4	0.6	0.8
D ₁	5.7	6.1	6.5	E	5.0	5.3	5.6
E ₁	6.3	6.6	6.9	e	--	1.27	--
e ₁	--	5.08	--	H _D	9.6	10.0	10.4
h ₁	2.1	2.3	2.5	L	0.80	1.0	1.2
L ₁	2.6	2.9	3.2	L ₂	0.35	0.65	0.95

Customer Service

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